Tool ID: 214
Tool Location: 111

Equipment Information Sheet

Oxford 81 Etcher

Manager: Philip Schneider 607-254-4931
Backup: Aaron Windsor 607-254-4831

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during normal operation
- Users must remain in the lab will the plasma is running

USAGE RESTRICTIONS

- No buddy system restrictions imposed on normal operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 2 hour block reservation
- Maximum 2 reservations in advance at any time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No gold or silver etching
- No high vapor pressure materials (lead, indium, ITO)
- No microscope slides
- Do not exceed maximum RF power of 300W
- Do not clean chamber with wipes or solvent. Report contamination to tool manager

Last Updated: 03/26/2025